

Major Ratings and Characteristics

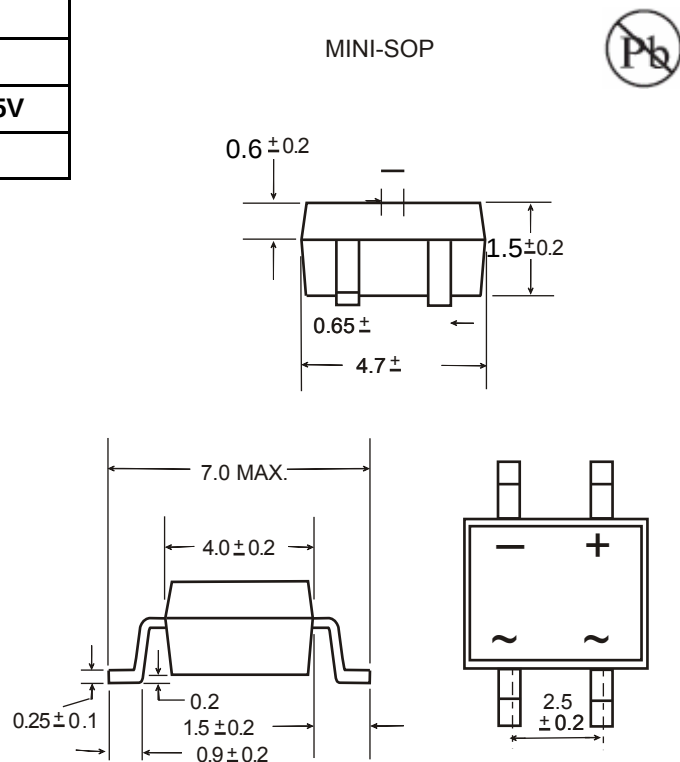
$I_{F(AV)}$	1.0 A
V_{RRM}	20 V to 100 V
I_{FSM}	30 A
V_F	0.50 V, 0.55V, 0.70 V, 0.85V
$T_j \text{ max.}$	125 °C

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- **Case:** MBF molded plastic body over Schottky barrier chips
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Polarity symbols marked on body



Dimensions in millimeters(1mm =0.0394")

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

($T_A = 25^\circ\text{C}$ unless otherwise noted)

	Symbol	KMB12F	KMB14F	KMB16F	KMB18F	KMB110F	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	V
Maximum DC blocking voltage	V _{DC}	20	40	60	80	100	V
Maximum average forward rectified current 0.2×0.2"(5.0×5.0mm)copper pad area	I _{F(AV)}	1.0					A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30					A
Maximum instantaneous forwad voltage at 1.0A	V _F	0.50	0.55	0.70	0.85		V
Maximum DC reverse current T _A = 25 °C at Rated DC blocking voltage T _A = 100°C	I _R	0.5 20					mA
Typical Junction Capacitance at 4.0V,1.0MHz	C _J	250			125		pF
Typical Thermal resistance (Note1)	R _{θJA} R _{θJL}	85 20					°C/ W
Operating junction temperature range	T _J	−55 to +125					°C
Storage temperature range	T _{STG}	− 55 to +150					°C

Note: 1.Thermal resistance from junction to ambient and from junction to lead P.C.B.mounted on 0.2×0.2"(5.0×5.0mm)copper pad areas.

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Fig.1 Forward Current Derating Curve

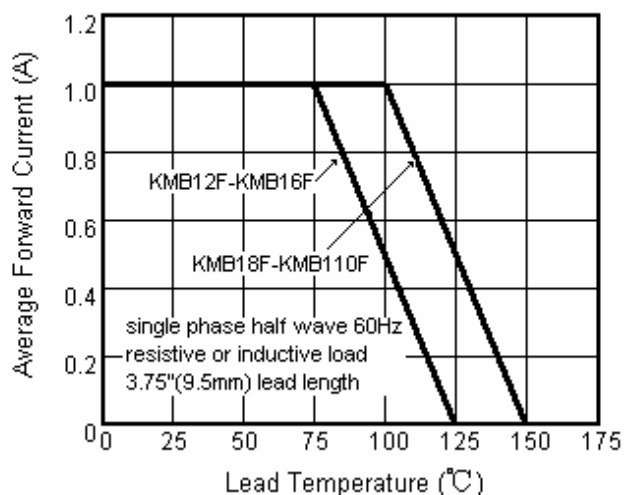


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

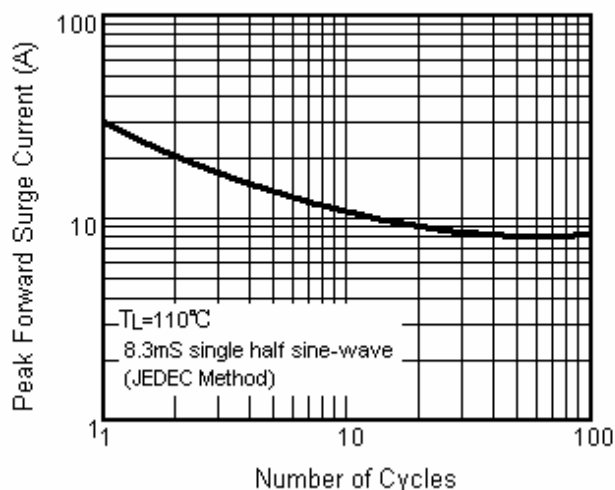


Fig.3 Typical Instantaneous Forward Characteristics

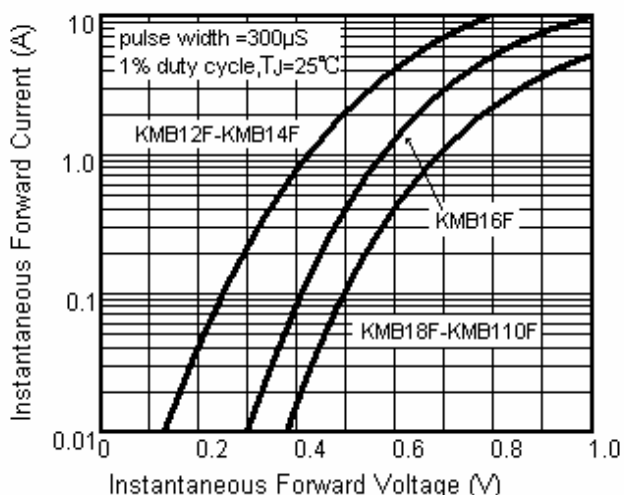


Fig.4A Typical Reverse Characteristics

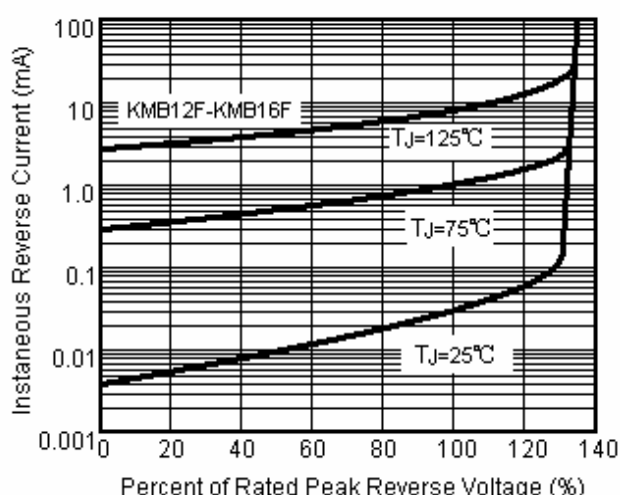


Fig.5 Typical Junction Capacitance

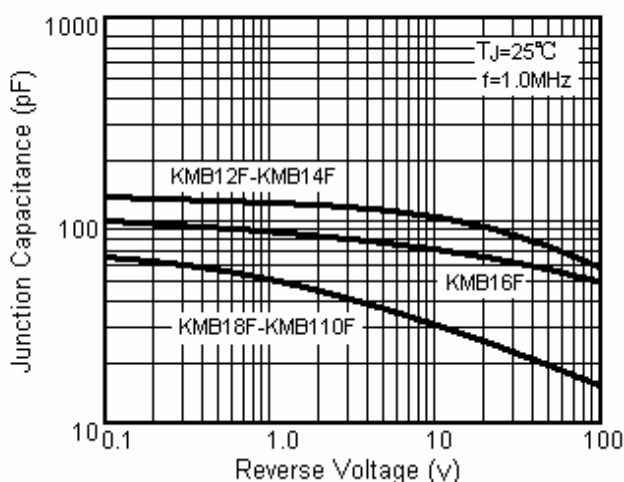


Fig.4B Typical Reverse Characteristics

